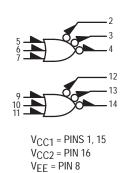
# **Dual 3-Input 3-Output NOR Gate**

The MC10H211 is designed to drive up to six transmission lines simultan—eously. The multiple outputs of this device also allow the wire "OR"—ing of several levels of gating for minimization of gate and package count.

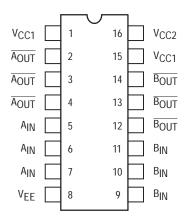
The ability to control three parallel lines with minimum propagation delay from a single point makes the MC10H211 particularly useful in clock distribution applications where minimum clock skew is desired.

- Propagation Delay, 1.0 ns Typical
- Power Dissipation, 160 mW Typical
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K-Compatible

#### LOGIC DIAGRAM



# DIP PIN ASSIGNMENT



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



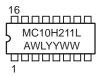
# ON Semiconductor

http://onsemi.com

### MARKING DIAGRAMS



CDIP-16 L SUFFIX CASE 620





PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

#### **ORDERING INFORMATION**

	1	
Device	Package	Shipping
MC10H211L	CDIP-16	25 Units/Rail
MC10H211P	PDIP-16	25 Units/Rail
MC10H211FN	PLCC-20	46 Units/Rail

# **MAXIMUM RATINGS**

Symbol	Characteristic	Rating	Unit
VEE	Power Supply (V <sub>CC</sub> = 0)	-8.0 to 0	Vdc
VI	Input Voltage (V <sub>CC</sub> = 0)	0 to VEE	Vdc
l <sub>out</sub>	Output Current – Continuous – Surge	50 100	mA
TA	Operating Temperature Range	0 to +75	°C
T <sub>stg</sub>	Storage Temperature Range – Plastic – Ceramic	−55 to +150 −55 to +165	ိ

# **ELECTRICAL CHARACTERISTICS** ( $V_{EE} = -5.2 \text{ V} \pm 5\%$ ) (See Note 1.)

		<b>0</b> °		25°		75°		
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
ΙE	Power Supply Current	_	42	-	38	_	42	mA
linH	Input Current High	_	720	-	450	_	450	μΑ
l <sub>inL</sub>	Input Current Low	0.5	_	0.5	-	0.3	-	μΑ
V <sub>OH</sub>	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
VOL	Low Output Voltage	-1.95	-1.63	-1.95	-1.63	-1.95	-1.60	Vdc
VIH	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
V <sub>IL</sub>	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

#### **AC PARAMETERS**

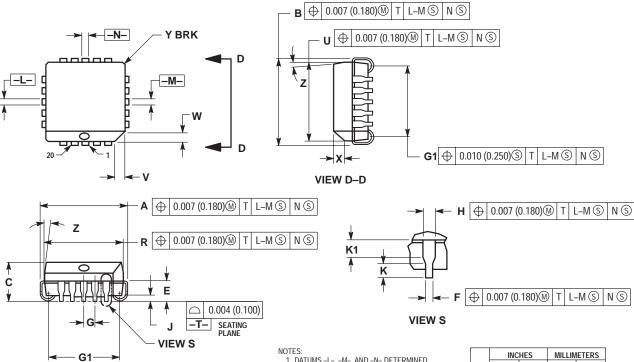
	<sup>t</sup> pd	Propagation Delay	0.7	1.6	0.7	1.6	0.7	1.7	ns
	t <sub>r</sub>	Rise Time	0.9	2.0	0.9	2.2	0.9	2.4	ns
Γ	t <sub>f</sub>	Fall Time	0.9	2.0	0.9	2.2	0.9	2.4	ns

Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been
established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is
maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts. Note: If crosstalk is present, double bypass capacitor to 0.2
μF.

# **PACKAGE DIMENSIONS**

#### PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



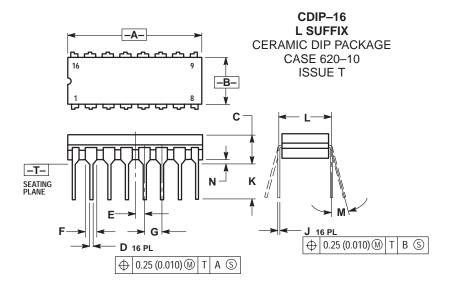
⊕ 0.010 (0.250)⑤ T L-M ⑤ N ⑤

- DATUMS -L-, -M-, AND -N- DETERMINED
   WHERE TOP OF LEAD SHOULDER EXITS PLASTIC WILLY LOVE LEAD STOUDER EXTRA FRAST BODY AT MOLD PARTING LINE.

  2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

  3. DIMENSIONS R AND U DO NOT INCLUDE MOLD
- FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
  4. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. 5. CONTROLLING DIMENSION: INCH.
- 6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

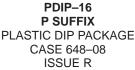
	INC	HES	MILLIN	IETERS			
DIM	MIN	MAX	MIN	MAX			
Α	0.385	0.395	9.78	10.03			
В	0.385	0.395	9.78	10.03			
С	0.165	0.180	4.20	4.57			
Ε	0.090	0.110	2.29	2.79			
F	0.013	0.019	0.33	0.48			
G	0.050	BSC	1.27	BSC			
Н	0.026	0.032	0.66	0.81			
J	0.020		0.51				
K	0.025		0.64				
R	0.350	0.356	8.89	9.04			
U	0.350	0.356	8.89	9.04			
٧	0.042	0.048	1.07	1.21			
W	0.042	0.048	1.07	1.21			
Χ	0.042	0.056	1.07	1.42			
Υ		0.020		0.50			
Z	2°	10 °	2 °	10 °			
G1	0.310	0.330	7.88	8.38			
K1	0.040		1.02				

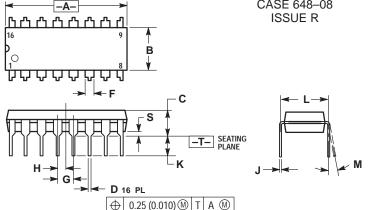


#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
  DIMENSION L TO CENTER OF LEAD WHEN
- FORMED PARALLEL.
  DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC

	INC	HES	MILLIMETERS		
DIM	IM MIN MAX		MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С	0.200			5.08	
D	0.015	0.020	0.39	0.50	
Е	0.050 BSC		1.27 BSC		
F	0.055 0.065		1.40	1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62	BSC	
M	0°	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	





#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIMENSION B DOES NOT INCLUDE MOLD FLASH.
- ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIN	IETERS		
DIM	MIN	MAX	MIN	MAX		
Α	0.740	0.770	18.80	19.55		
В	0.250	0.270	6.35	6.85		
С	0.145	0.175	3.69	4.44		
D	0.015	0.021	0.39	0.53		
F	0.040	0.70	1.02	1.77		
G	0.100	0.100 BSC		2.54 BSC		
Н	0.050	BSC	1.27 BSC			
J	0.008	0.015	0.21	0.38		
K	0.110	0.130	2.80	3.30		
L	0.295	0.305	7.50	7.74		
M	0°	10 °	0 °	10 °		
S	0.020	0.040	0.51	1.01		

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